

IN THE CLAIMS

Claims 1-40: Canceled.

41. (Currently Amended) An interface material for electronic devices comprising at least one compliant resin material and at least one solder material comprising indium, silver, copper, aluminum, tin, bismuth, gallium and alloys thereof, silver-coated copper, silver-coated aluminum and combinations thereof, wherein the interface material further comprises at least one wetting enhancer.
42. (Previously Presented) The interface material of claim 41, wherein the interface material comprises at least about 50 weight percent of the at least one solder material.
43. Canceled.
44. (Previously Presented) The interface material of claim 41 wherein the at least one resin material comprises a silicone resin.
45. (Currently Amended) The interface material of claim ~~[[43]]~~ 44, wherein the silicone resin comprises a vinyl terminated siloxane, a reinforcing additive, a crosslinker and a catalyst.
46. (Currently Amended) The interface material of claim ~~[[44]]~~ 45, wherein the vinyl terminated siloxane is vinyl silicone.
47. (Currently Amended) The interface material of claim ~~[[44]]~~ 45, wherein the reinforcing additive is vinyl Q resin.
48. (Currently Amended) The interface material of claim ~~[[44]]~~ 45, wherein the crosslinker comprises a hydride functional siloxane.
49. (Currently Amended) The interface material of claim ~~[[44]]~~ 45, wherein the catalyst comprises a platinum complex.
50. (Previously Presented) The interface material of claim ~~49~~, wherein the platinum complex is a platinum-vinylsiloxane compound.

51. (Currently Amended) The interface material of claim ~~[[42]]~~ 41, wherein the wetting enhancer comprises an organo-titanite compound.
52. (Previously Presented) The interface material of claim 41, wherein the at least one solder material comprises an indium-based alloy or compound.
53. (Previously Presented) The interface material of claim 52, wherein the indium-based alloy or compound comprises InSn, InAg or In.
54. (Previously Presented) The interface material of claim 41, wherein the at least one solder material comprises a tin-based alloy or compound.
55. (Previously Presented) The interface material of claim 54, wherein the tin-based alloy or compound comprises SnAgCu or SnBi.
56. (Previously Presented) The interface material of claim 41, wherein the interface material comprises one of an aluminum or an aluminum-based alloy or compound.
57. (Previously Presented) The interface material of claim 41, further comprising a filler material..
58. (Currently Amended) The interface material of claim ~~[[56]]~~ 57, wherein the filler material comprises carbon microfibers.
59. (Previously Presented) The interface material of claim 41, wherein the at least one resin material is also crosslinkable.
60. (Previously Presented) The interface material of claim 42, wherein the at least one solder material is present in an amount of at least about 60 weight percent.
61. (Previously Presented) The interface material of claim 60, wherein the at least one solder material is present in an amount of at least about 70 weight percent.
62. (Previously Presented) The interface material of claim 61, wherein the at least one solder material is present in an amount of at least about 80 weight percent.
63. (Previously Presented) A layered material comprising the interface material of claim 41.

Honeywell Docket No. JM35978 CIP2 DIV - 4018
Buchalter Docket No.: H9925-2010 (7220154001-3002431)

64. (Previously Presented) A layered material comprising the interface material of claim 42.